

ABSTRACT OF DISCLOSURE

A process for fabricating a cavity-type integrated circuit package. The process includes: supporting an interior portion of each of a plurality of leads, in a mold; 5 supporting a die attach pad in said mold; molding a package body in said mold such that said leads extend from an interior cavity of said package body to an exterior thereof; mounting a semiconductor die to said die attach pad; wire bonding various ones of said leads to said semiconductor die; adding a fill material for covering at least a surface of said interior portion of said leads; and mounting a lid on said 10 package body for enclosing said die in said cavity of said package body.